JC17 Rec'd TCT/PTO 22 JUN 2005

5. A method of manufacturing an electronic part according to claim 4, characterized in that a thickness of the thin film insulating layer is between 1 to 15 μm .

5

6. A method of manufacturing an electronic part according to any one of claims 1 to 5, characterized in that the columnar conductor is formed by a metal plating process.

10

- 7. (Deleted)
- 8. (Deleted)